

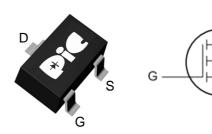
### General Description

This PAN2554N N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

### > Feature

- ●Super Low Gate Charge
- ●Green Device Available
- ●Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- ●SOT-23 Package design

### > **SOT-23**



### Application

- ■Load Switch
- Portable instrument
- ●MB / NB / 3C device

### > Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =25°C	3.6	А
Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> =70°C	2.8	А
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	14.4	Α
Total Power Dissipation <sup>3</sup>	P <sub>D</sub> @T <sub>A</sub> =25°C	1	W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	W
Operating Junction Temperature Range	TJ	55 to 150	°C
Thermal Resistance Junction-ambient <sup>1</sup>	R <sub>θ</sub> ЈА	125	°C
Thermal Resistance Junction-Case <sup>1</sup>	R <sub>eJC</sub>	80	°C/W



# N-Ch 20V Fast Switching MOSFET $V_{DS}$ =20V, $I_D$ =3.6A, $RDS_{(ON)}$ =55m $\Omega$

## Electrical Characteristics (T<sub>J</sub>=25 C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	BVDSS	Vgs=0V , Ib=250uA	20			V
Static Drain-Source On-Resistance2	Rds(on)	Vgs=4.5V , ID=3A			55	mΩ
	KDS(ON)	Vgs=2.5V , Ip=2A			75	
Gate Threshold Voltage	VGS(th)	Vgs=Vds, Id=250uA	0.4		1.2	V
Drain-Source Leakage Current	lana	Vps=16V , Vgs=0V , Tj=25°C				
	IDSS	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
Gate-Source Leakage Current	Igss	Vgs=±12V, Vds=0V			±100	nA
Forward Transconductance	gfs	VDS=5V, ID=3A		10.5		S
Total Gate Charge (4.5V)	Qg			4.6		
Gate-Source Charge	Qgs	VDS=15V , VGS=4.5V , ID=3A		0.7		nC
Gate-Drain Charge	Qgd			1.5		
Turn-On Delay Time	T <sub>d(on)</sub>			1.6		
Rise Time	Tr	VDD=10V, VGS=4.5V,		42		
Turn-Off Delay Time	T <sub>d(off)</sub>	Rg=3.3ΩID=3A		14		ns ns
Fall Time	Tf			7		
Input Capacitance	Ciss			310		
Output Capacitance	Coss	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		49		рF
Reverse Transfer Capacitance	Crss			35		

## Diode Characteristics

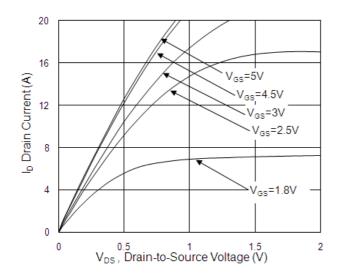
Parameter	Symbol	Conditions Min.		Тур.	Max.	Unit
Continuous Source Current <sub>1,4</sub>	ls	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			3.6	Α
Diode Forward Voltage2	VsD	Vgs=0V , Is=1A , TJ=25°C			1.2	V

#### Note

- 1. Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.Ensure that the channel temperature does not exceed 150°C.
- 4.The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



## > Typical Characteristics



**Fig.1 Typical Output Characteristics** 

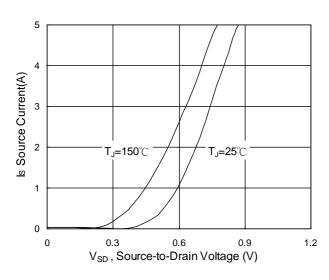


Fig.3 Forward Characteristics of Reverse

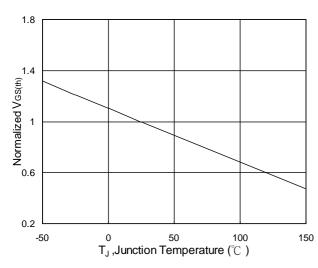


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

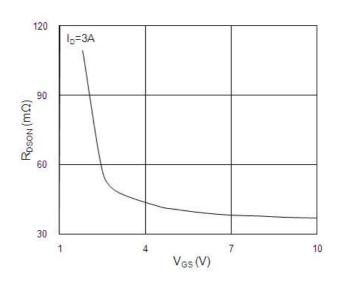


Fig.2 On-Resistance vs. Gate-Source Voltage

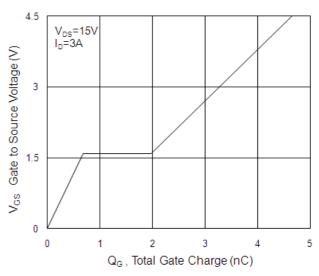


Fig.4 Gate-Charge Characteristics

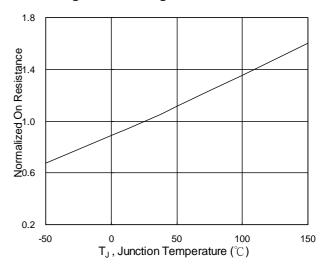
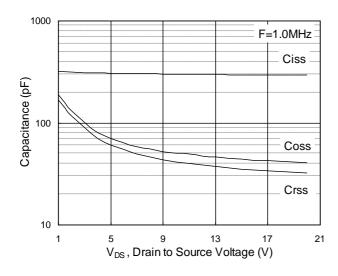


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





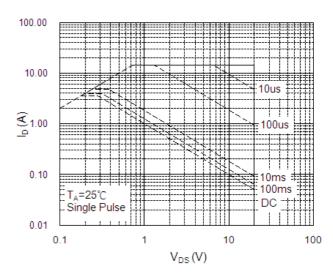


Fig.7 Capacitance

Fig.8 Safe Operating Area

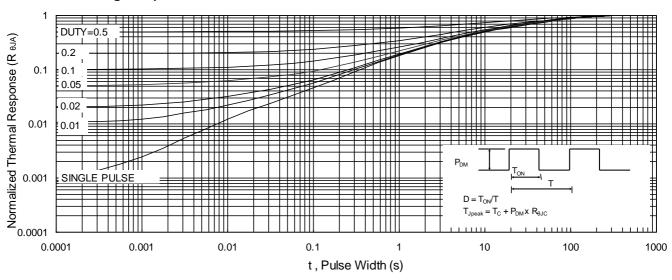
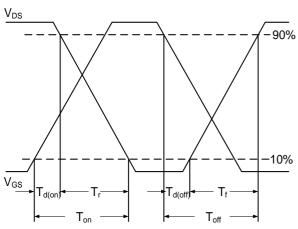


Fig.9 Normalized Maximum Transient Thermal Impedance





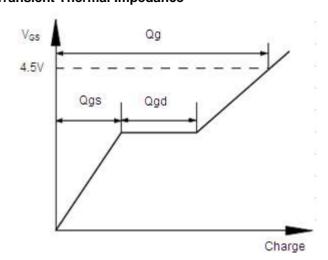
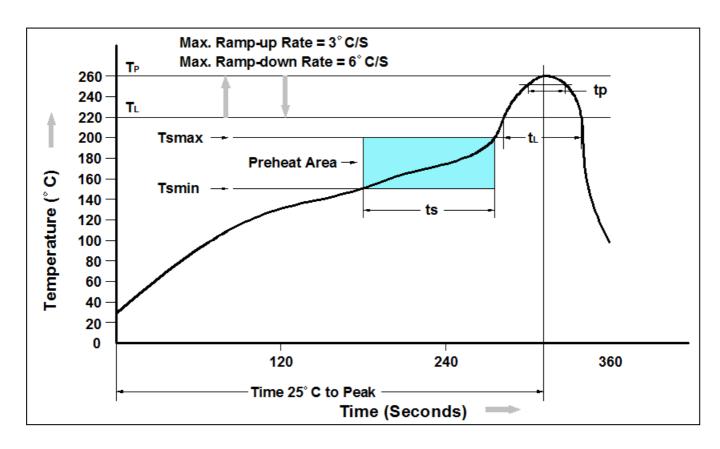


Fig.11 Gate Charge Waveform



## Recommand IR Reflow Soldering Thermal Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Average Ramp-up Rate (tL to tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Temperature	260°C +0°C /-5°C
Time (tP) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

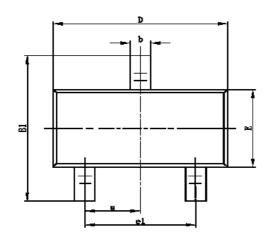
## Ordering Information

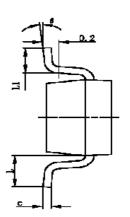
Part Number	Description	Quantity
PAN2554N	SOT-23 Reel	3000 pcs

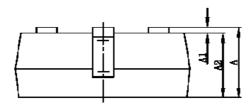


N-Ch 20V Fast Switching MOSFET  $V_{DS}$ =20V,  $I_D$ =3.6A,  $RDS_{(ON)}$ =55m $\Omega$ 

## Package Information (SOT-23)







Sumb al	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.400	0.012	0.016	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950TYP		0.03	7TYP	
e1	1.800	2.000	0.071	0.079	
L	0.700REF		0.028REF		
L1	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	





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